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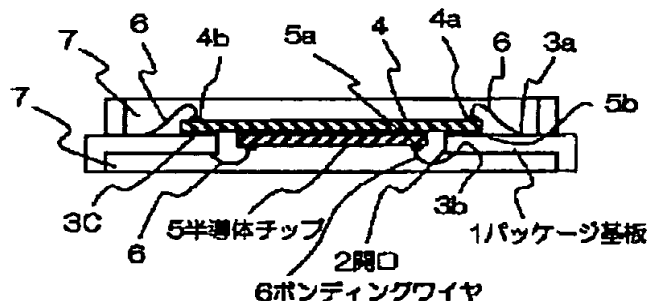
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TITLE : SEMICONDUCTOR DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To perform high density mounting of a semiconductor chip by utilizing the technique of wire bonding process to both of stacked semiconductor chips.

SOLUTION: For this semiconductor device, one of stacked semiconductor chips 4 and 5 is hooked to the peripheral part of an opening 2 of a package substrate 1 and mounted on the substrate 1, the other semiconductor chip 5 stacked on the semiconductor chip 4 mounted on the substrate 1 is incorporated inside the opening 2 of the package substrate 1, and the electrodes 4a and 5a of both of the stacked semiconductor chips 4 and 5 and bonding pads 3a and 3b of the package substrate 1 are respectively connected with a bonding wire 6.

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